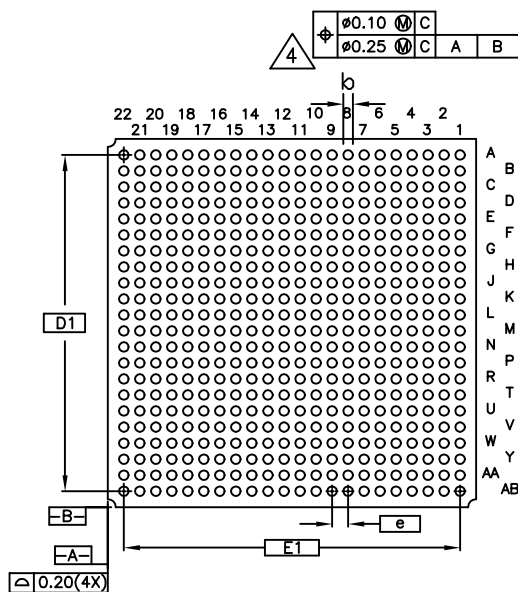
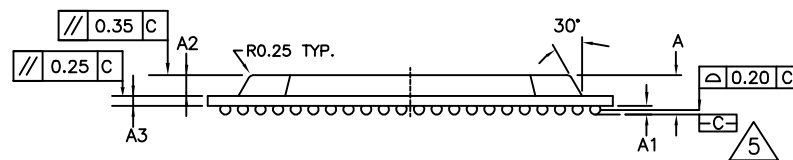


TOP VIEW



BOTTOM VIEW
(BALL SIDE)

DIMENSIONAL REFERENCES			
REF.	MIN.	NOM.	MAX.
A	1.90	2.03	2.16
A1	0.40	0.50	0.60
A2		0.97 REF	
A3		0.56 REF	
D		23.00	
D1		21.00 BSC	
E		23.00	
E1		21.00 BSC	
b		0.60	
e		1.0 BSC	
M		22	
N		484	
Pkg. Code: V484T-4			



SIDE VIEW

NOTES:

- ALL DIMENSIONS ARE IN MILLIMETERS.
- 'e' REPRESENTS THE BASIC SOLDER BALL PITCH.
- 'M' REPRESENTS THE BASIC SOLDER BALL MATRIX SIZE. 'N' IS THE NUMBER OF ATTACHED SOLDER BALLS.
- 'b' IS MEASURABLE AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO THE PRIMARY DATUM [C].
- PRIMARY DATUM [C] AND THE SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- THE OVERALL PACKAGE THICKNESS "A" ALREADY CONSIDERS COLLAPSE BALLS.
- REFERENCE JEDEC MO-205.
- MARKING SHOWN IS FOR PKG. ORIENTATION ONLY.
- ALL DIMENSIONS APPLY TO BOTH LEADED (-) AND PbFREE (+) PKG. CODES.

MAXIM

TITLE:
PACKAGE OUTLINE,
484 BALL BGA, 23x23x2.03mm

APPROVAL	DOCUMENT CONTROL NO.	REV.	1/1
	21-0447	A	